

## ABSTRACT OF THE DISCLOSURE

An electronic package that may include a first bond pad and a second bond pad located on a bond shelf. The  
5 bond shelf may have an edge. The package may have a first  
conductive bus that may be connected to the first bond pad  
by a first conductive strip that extends along the edge of  
the bond shelf. The package may also have a second  
conductive bus that may be connected to the second bond pad  
10 by a second conductive strip that extends along the edge of  
the bond shelf.